Our compact design is mountable on .100 inch centers and is available with radius pins for connector mating. Designed to MIL-F-15733. Available in capacitance values up to 10,000 pF GMV (+100% / -0).

### ALUMINUM COMPATIBLE

**Voltage Rating**
50 VDC (higher available)

**Current Rating**
5 Amps Max

**Insulation Resistance**
Greater than 1.5 GΩ @ 25°C

**Dissipation Factor**
Less than 3% (except 10K pF less than 4%)

**Max. Temp.** / **Min. Temp.** / **Operating Range**
250°C / -65°C / -55°C to +125°C

**Leak Rate**
Less than 1 X 10⁻⁸ cc/sec @ 1 atm (He)

### SPECIFICATIONS

<table>
<thead>
<tr>
<th>PART NO.</th>
<th>CAPACITANCE VALUE (1)</th>
<th>SERIES</th>
<th>L1 ±0.005 (3)</th>
<th>L2 ±0.005 (3)</th>
<th>PLATING CODE (2)</th>
<th>MATERIAL</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cxxx</td>
<td>74A25</td>
<td>xxx</td>
<td>xxx</td>
<td>02</td>
<td>9013</td>
<td>Steel</td>
</tr>
</tbody>
</table>

Example Part No: C103-74A25-225-075-02

**NOTES:**

1. Specify capacitance value. Enter first two digits of value then the number of zeros that follow. Example: C103 equals 10,000 pF.
2. Standard plating is 50 microinches minimum GOLD per MIL-G-45204, Type III, Grade A over 200-400 microinches NICKEL per MIL-C-26074. Plating thickness is measured on pin.
3. Standard pin termination is straight-cut. Special pin terminations are also available (See Bulletin 100, pg 3).
4. Short term process temperature.
5. Storage temperature.
6. See Bulletin 200 for solder preforms.

All dimensions are inches.
HERMETIC CAPACITORS
74A25 Series

APPLICATION DATA

PROTRUDING MOUNT

FLUSH MOUNT

HOUSING PREPARATION

<table>
<thead>
<tr>
<th>PROTRUDING MOUNT</th>
<th>FLUSH MOUNT</th>
</tr>
</thead>
<tbody>
<tr>
<td>DRILL .063 ± .002 THRU</td>
<td>DRILL .063 ± .002 THRU</td>
</tr>
<tr>
<td>C’BORE .077 ± .001 DIA. x .055 ± .002 DP.</td>
<td>C’BORE .077 ± .001 DIA. x .130 ± .002 DP.</td>
</tr>
<tr>
<td>C’BORE .140 ± .002 DIA. x .030 ± .002 DP.</td>
<td>C’BORE .140 ± .002 DIA. x .105 ± .002 DP.</td>
</tr>
</tbody>
</table>

All dimensions are inches.